

Supply Chain Explorer

By the Emerging Technology Observatory

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Assembly and packaging

At the end of the fabrication process, the finished wafer contains dozens of chips in a grid pattern. During assembly and packaging, the wafer is separated into individual chips, or "dies". Each chip is mounted on a frame with wires that connect the chip to external devices, and enclosed in a protective casing. This produces the familiar look of a dark gray rectangle with metal pins at the edges.